SGM822
3-Rail Power Sequencer with Programmable Timing

GENERAL DESCRIPTION

The SGM822 is an integrated, 3-rail power sequencer. It controls the power-up and power-down sequence of three power supplies by pulling their enable or shutdown pins high or low. Staggered start sequence can avoid the impact of latch conditions or large inrush current on system reliability.

This simple sequencer has three open-drain output flags. When the enable (EN) pin is pulled high, the flags are successively released from FLAG1 to FLAG3 after individual programmable delay time. Then the connected power supplies power up. When the EN pin is pulled low, the flags output low with a reverse sequence from FLAG3 to FLAG1 after individual programmable delay time. The delay time is programmed by connecting a capacitor between the TADJ pin and ground. The logic of the output flags can be inverted by the user.

The SGM822 is available in Green MSOP-8 and UTDFN-1.5×1.5-8L packages. It operates over an ambient temperature range of -40℃ to +125℃.

FEATURES

- **Up to 3-Rail Power Sequence Control**
- **Low Quiescent Current: 36μA (TYP)**
- **Input Voltage Range: 2.7V to 5.5V**
- **Pin-Selected Flag Output Logic**
- **Capacitor-Programmable Power-Up/Power-Down Sequencing Delay**
- **Available in Green MSOP-8 and UTDFN-1.5×1.5-8L Packages**

APPLICATIONS

Multivoltage Systems
Servers
Networking Systems
Telecom Equipment
Microprocessor, Microcontroller and FPGA Sequencing
Multiple Supply Sequencing

TYPICAL SYSTEM APPLICATION

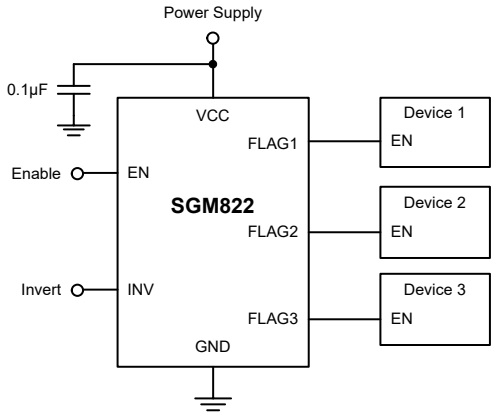


Figure 1. Typical System Application

TYPICAL APPLICATION

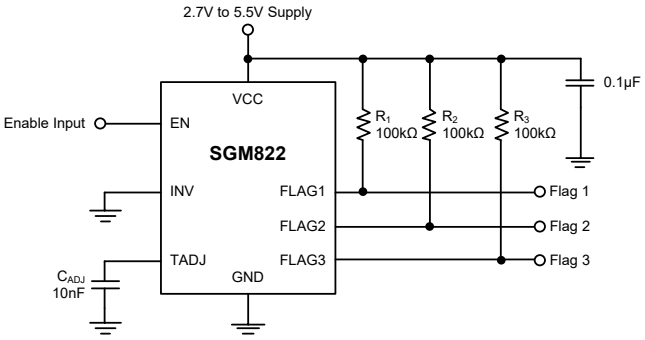


Figure 2. Typical Application Circuit

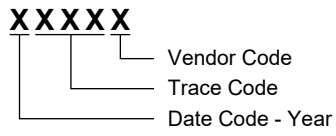
PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM822	MSOP-8	-40℃ to +125℃	SGM822XMS8G/TR	SGM822 XMS8 XXXXX	Tape and Reel, 4000
	UTDFN-1.5×1.5-8L	-40℃ to +125℃	SGM822XUDW8G/TR	0NE XXX	Tape and Reel, 4000

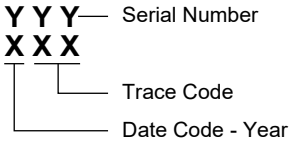
MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.

MSOP-8



UTDFN-1.5×1.5-8L



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

VCC, EN, INV, TADJ, FLAG1, FLAG2, FLAG3 to GND ..... -0.3V to 6V

Package Thermal Resistance

MSOP-8, θ_{JA} ..... 183.3℃/W

MSOP-8, θ_{JB} ..... 126.4℃/W

MSOP-8, θ_{JC} ..... 84.5℃/W

UTDFN-1.5×1.5-8L, θ_{JA} ..... 149.5℃/W

UTDFN-1.5×1.5-8L, θ_{JB} ..... 105.7℃/W

UTDFN-1.5×1.5-8L, θ_{JC} ..... 126.4℃/W

Junction Temperature ..... +150℃

Storage Temperature Range ..... -65℃ to +150℃

Lead Temperature (Soldering, 10s) ..... +260℃

ESD Susceptibility

HBM 4000V

CDM 1000V

RECOMMENDED OPERATING CONDITIONS

VCC to GND ..... 2.7V to 5.5V

EN, INV, TADJ, FLAG1, FLAG2, FLAG3 to GND ..... -0.3V to V_{CC} + 0.3V

Operating Junction Temperature Range ..... -40℃ to +125℃

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

ESD SENSITIVITY CAUTION

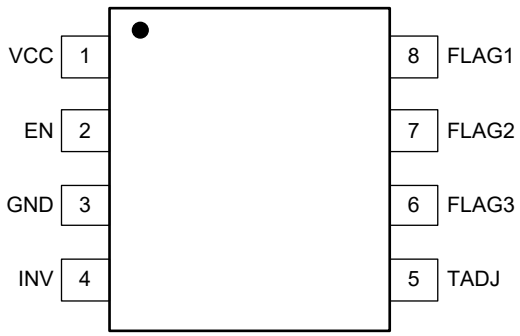
This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

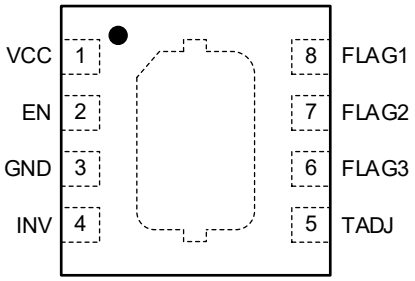
PIN CONFIGURATIONS

(TOP VIEW)



MSOP-8

(TOP VIEW)



UTDFN-1.5×1.5-8L

PIN DESCRIPTION

PIN	NAME	I/O	FUNCTION
1	VCC	I	Input Supply.
2	EN	I	Precision Enable.
3	GND	–	Ground.
4	INV	I	Output Logic Invert.
5	TADJ	O	Timer Adjustment.
6	FLAG3	O	Open-Drain Output 3.
7	FLAG2	O	Open-Drain Output 2.
8	FLAG1	O	Open-Drain Output 1.

NOTE: I: input; O: output.

ELECTRICAL CHARACTERISTICS

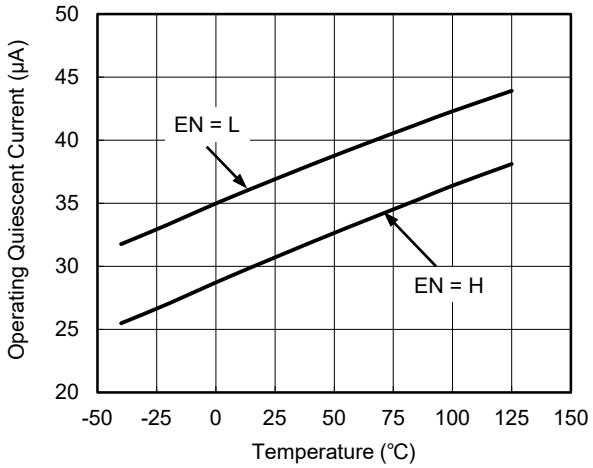
(V_{CC} = 3.3V, T_J = -40℃ to +125℃, typical values are measured at T_J = +25℃, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Operating Quiescent Current	I_Q	EN = H		30	55	μA
		EN = L		36	65	
FLAGx Leakage Current	I_{FLAG}	V_{FLAGx} = 3.3V		0.001	0.5	μA
		V_{FLAGx} = 6.0V			1.0	
FLAGx Output Voltage Low	V_{OL}	I_{FLAGx} = 1.2mA			0.3	V
TADJ Source Current	I_{TADJ_SRC}		7	11	15	μA
TADJ Sink Current	I_{TADJ_SNK}		7	11	15	μA
High Threshold Level	V_{HTH}		1.1	1.2	1.3	V
Low Threshold Level	V_{LTH}		0.4	0.5	0.6	V
Clock Cycle	t_{CLK}	C_{ADJ} = 10nF	1.10	1.30	1.45	ms
Flag Delay Time	t_{D1}, t_{D4}		9		10	Clock Cycles
	t_{D2}, t_{D3}, t_{D5}, t_{D6}			8		Clock Cycles
EN Pin Threshold	V_{EN}		1.1	1.2	1.3	V
EN Pin Pull-Up Current	I_{EN}	V_{EN} = 0V		6.5		μA
INV Pin V_{IH}	V_{IH_INV}		0.9 × V_{CC}			V
INV Pin V_{IL}	V_{IL_INV}				0.1 × V_{CC}	V

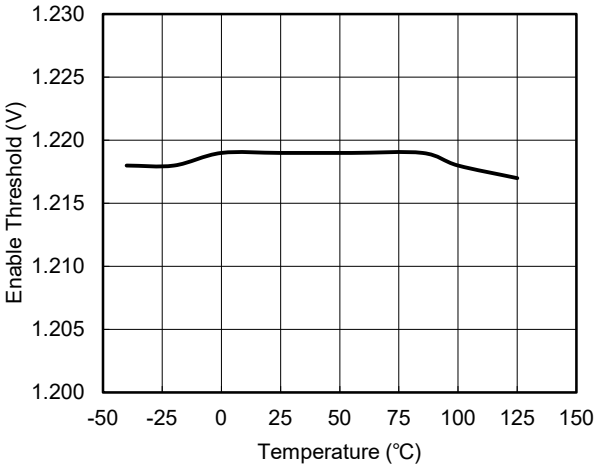
TYPICAL PERFORMANCE CHARACTERISTICS

V_{CC} = 3.3V, unless otherwise noted.

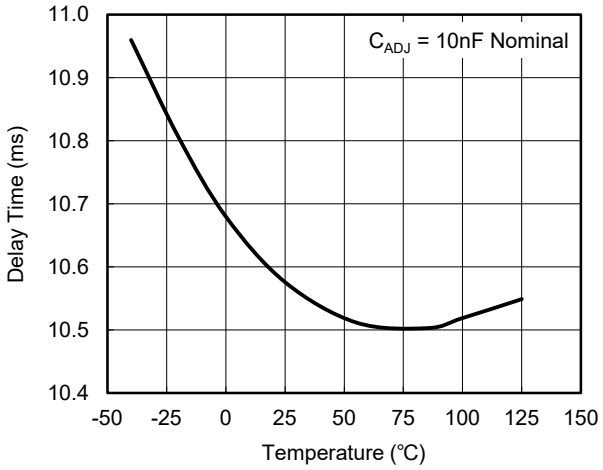
Operating Quiescent Current vs. Temperature



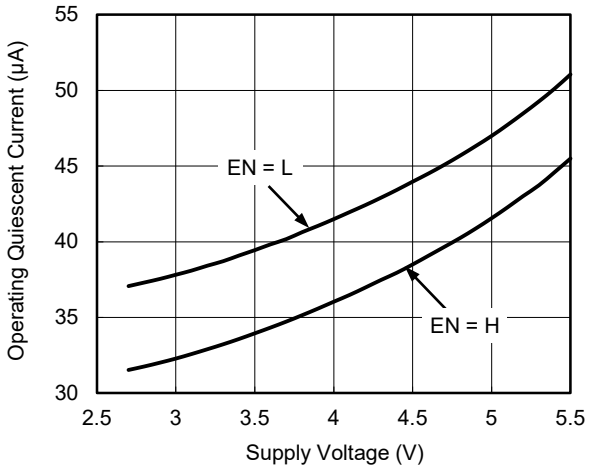
Enable Threshold vs. Temperature



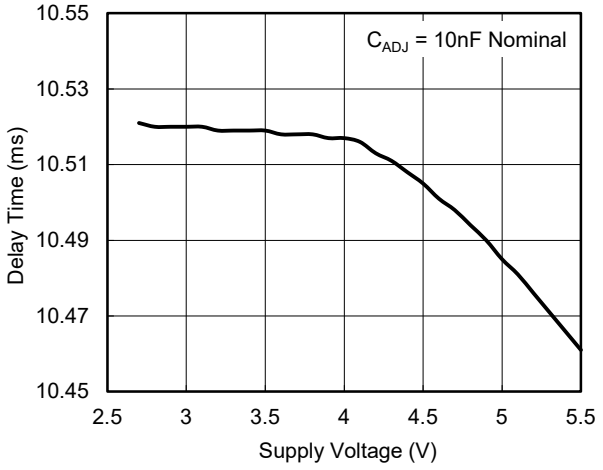
Delay Time vs. Temperature



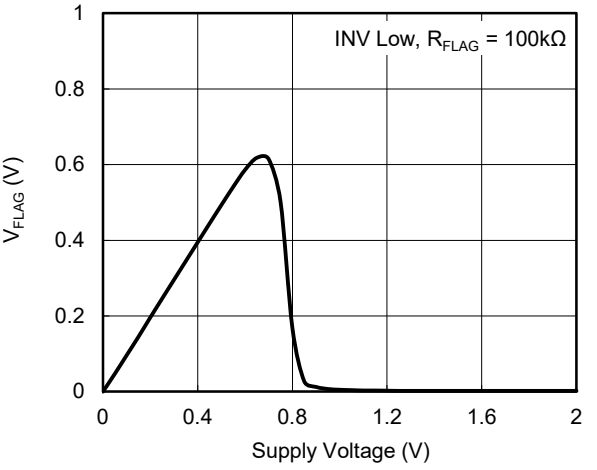
Operating Quiescent Current vs. Supply Voltage



Delay Time vs. Supply Voltage

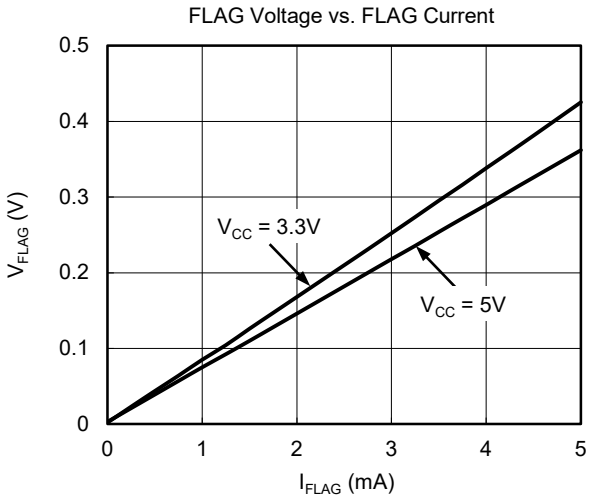


FLAG Voltage vs. Supply Voltage



TYPICAL PERFORMANCE CHARACTERISTICS (continued)

V_{CC} = 3.3V, unless otherwise noted.



FUNCTIONAL BLOCK DIAGRAM

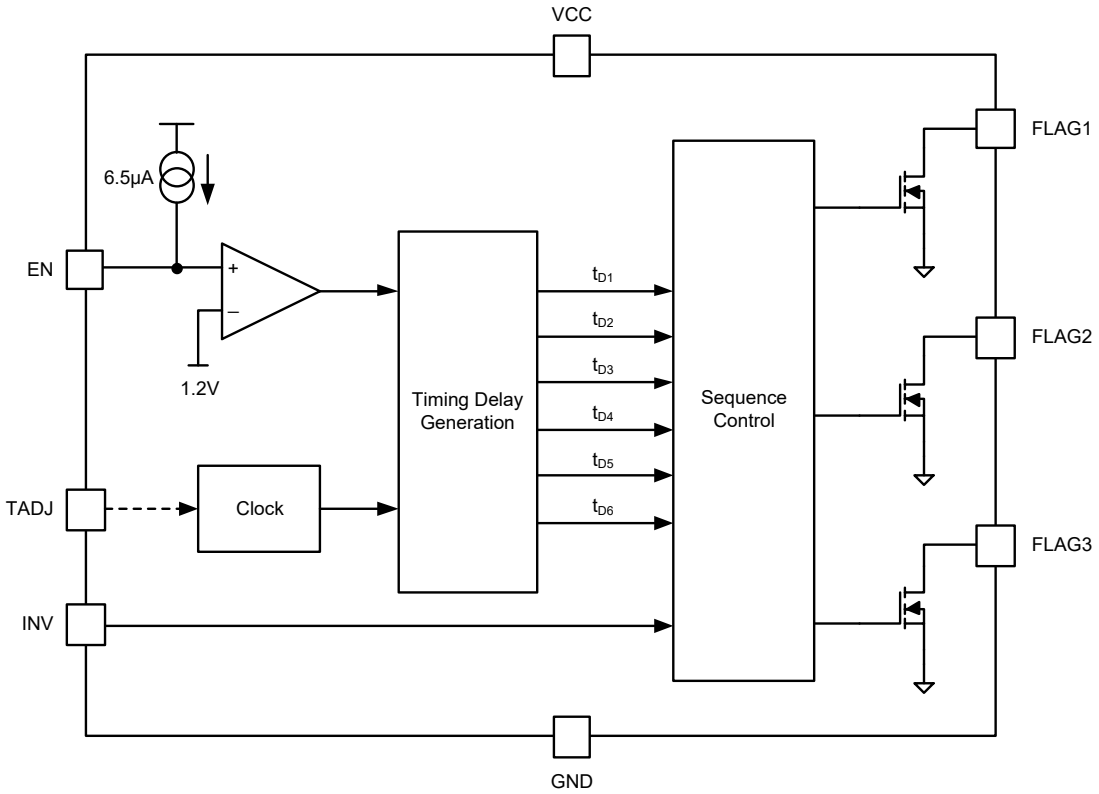


Figure 3. SGM822 Block Diagram

DETAILED DESCRIPTION

The SGM822 multivoltage power sequencer provides power-up and power-down control for up to three power supplies. Three output flags are connected to the enable or shutdown pins of the power supplies to control the operation. The delay time between each flag signals is programmed by the TADJ capacitor. These functions allow users to design a complex power system without the concern of large inrush currents or latch-up conditions that may cause the system abnormality or even damaged. The user can use the invert (INV) pin to reverse the logic of the flag outputs. The INV pin is not allowed to be floating. The following discussion assumes INV is held low so that the flag output is active high.

Adjustable Timing

An external timing capacitor is connected between the TADJ pin and ground that establishes the clock waveform. The SGM822 linearly charges or discharges this capacitor by a fixed current source/sink, denoted $I_{TADJ\_SRC}/I_{TADJ\_SNK}$, of magnitude 11μA between predefined threshold voltage levels, denoted V_{HTH} and V_{LTH}. Figure 4 shows the timing waveform. Once the capacitor voltage drops to V_{LTH}, the chip reverses to charge again. With this method, the clock cycle is generated.

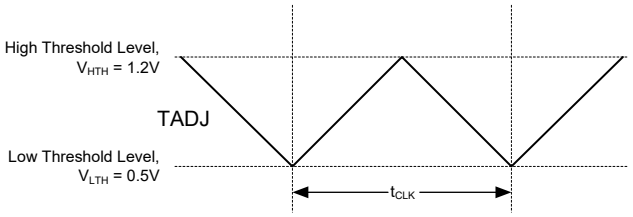


Figure 4. TADJ Pin Timing Waveform

The clock cycle period is directly proportional to the timing capacitor value. Considering the TADJ threshold voltage levels and the charge/discharge current magnitude, it can be shown that the timing capacitor-clock period relationship is typically 130μs/nF. For example, a 10nF capacitor sets up a clock period of 1.3ms.

The flag outputs are controlled by the enable (EN) pin. After power-on, all the flags are held low until the precision EN voltage exceeds its threshold. After EN is asserted, the open-drain flags will be sequentially released.

The first flag (FLAG1) is released after a fixed time period, denoted t_{D1} in Figure 5. This corresponds to least nine, maximum ten, clock cycles depending on where EN is asserted relative to the clock signal. After the release of the first flag, another timing procedure will begin to delay the release of the second flag (FLAG2). This timing procedure simultaneously begins when the timing capacitor starts charging. As a result, the delay time, denoted t_{D2}, corresponds to exactly eight clock periods. Similarly, FLAG3 is released after the delay time, denoted t_{D3}, again eight clock cycles, has expired. A 10nF TADJ capacitor generates typical delay time t_{D2} and t_{D3} of 10.4ms and t_{D1} of from 11.7ms to 13ms.

The power-down sequence is the same as power-up, but in reverse order. When EN is pulled low, the third flag (FLAG3) is pulled low after the delay time, denoted t_{D4}, has expired. The second and first flags will then follow in a sequential manner after the corresponding delay time. The delay time, denoted t_{D4}, t_{D5}, t_{D6}, is equal to t_{D1}, t_{D2}, t_{D3}, respectively.

For robustness, the internal pull-down FET of each flag is designed to limit the sink current level so that it can sustain a short circuit to VCC for a short period.

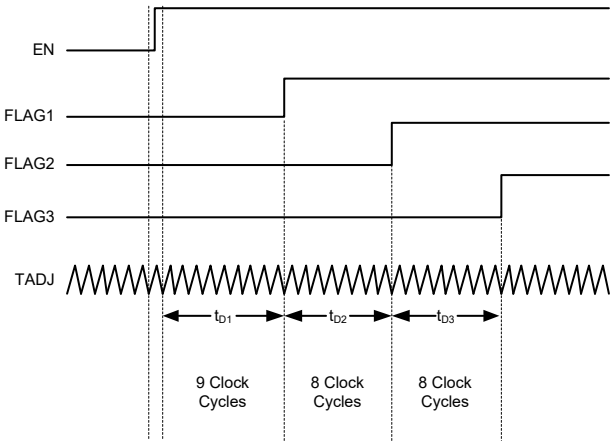


Figure 5. Power-Up Sequence, INV Low

DETAILED DESCRIPTION (continued)

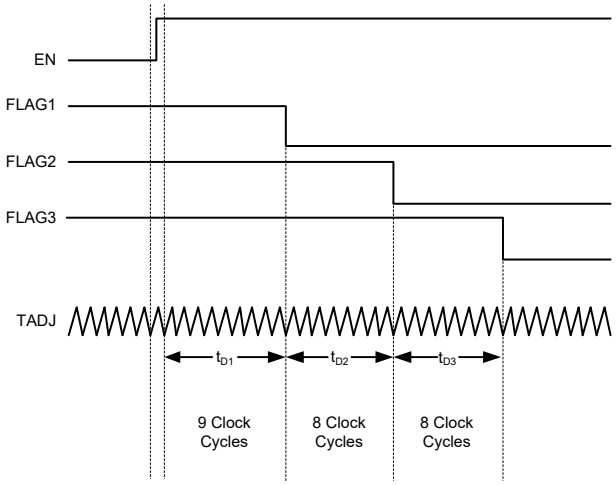


Figure 6. Power-Up Sequence, INV High

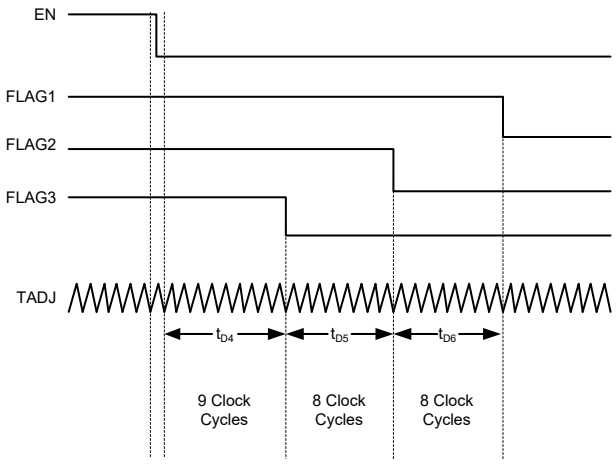


Figure 7. Power-Down Sequence, INV Low

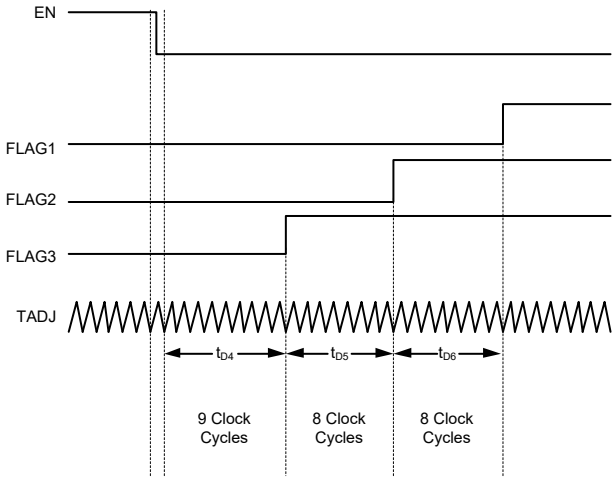


Figure 8. Power-Down Sequence, INV High

DETAILED DESCRIPTION (continued)

Enable Circuit

The enable circuit is designed with an internal comparator, an accurate bandgap voltage (1.2V, TYP), to provide a precision enable threshold. With this precision enable function, the user can use an external capacitor to set the timing as shown in Figure 9.

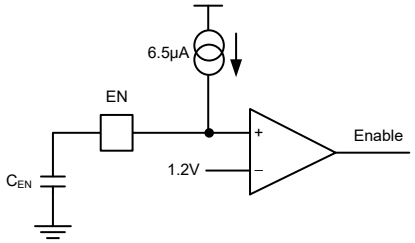


Figure 9. Precision Enable Circuit

Using the internal current source to charge the external capacitor C_{EN}, assuming EN is charging from 0V, the delay time can be calculated by the equation as follows.

$$t_{ENABLE\_DELAY} = \frac{1.2V \times C_{EN}}{6.5\mu A} \quad (1)$$

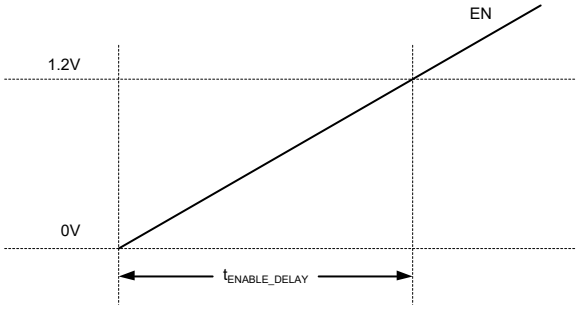


Figure 10. Enable Delay Timing

Alternatively, sequencing can be based on a certain event. For example, connect the power supply of SGM822 to EN pin through a resistor divider, as shown in Figure 11. After the VCC voltage exceeds the threshold voltage, the sequencing begins to execute. When calculating the VCC threshold voltage that triggers the sequencing event, take care of the effects of the internal EN pull-up current source. The supply voltage for which EN is asserted is given by:

$$VCC_{ENABLE} = 1.2V \times \left(1 + \frac{R_{EN1}}{R_{EN2}}\right) - 6.5\mu A \times R_{EN1} \quad (2)$$

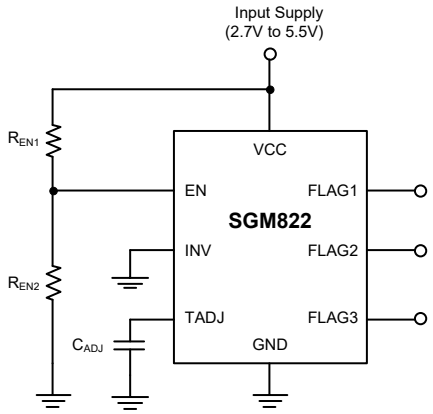


Figure 11. Enable Based On Input Supply Level

The EN pin provides the glitch-free feature to make the system robust. The timer will start counting at the EN rising edge, but will always reset if EN is pulled low before FLAG1 is released. This is illustrated in Figure 12 with INV low.

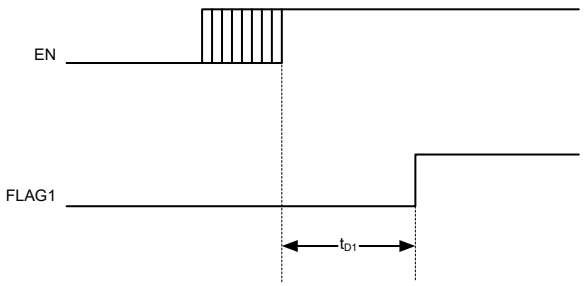


Figure 12. Enable Glitch Timing, INV Low

If EN is pulled low before the complete power-up sequence, the SGM822 will enter a controlled shutdown. Figure 13 describes the flag sequence if EN is pulled low after FLAG1 releases, but before the entire power-up sequence is completed. INV is assumed low.

DETAILED DESCRIPTION (continued)

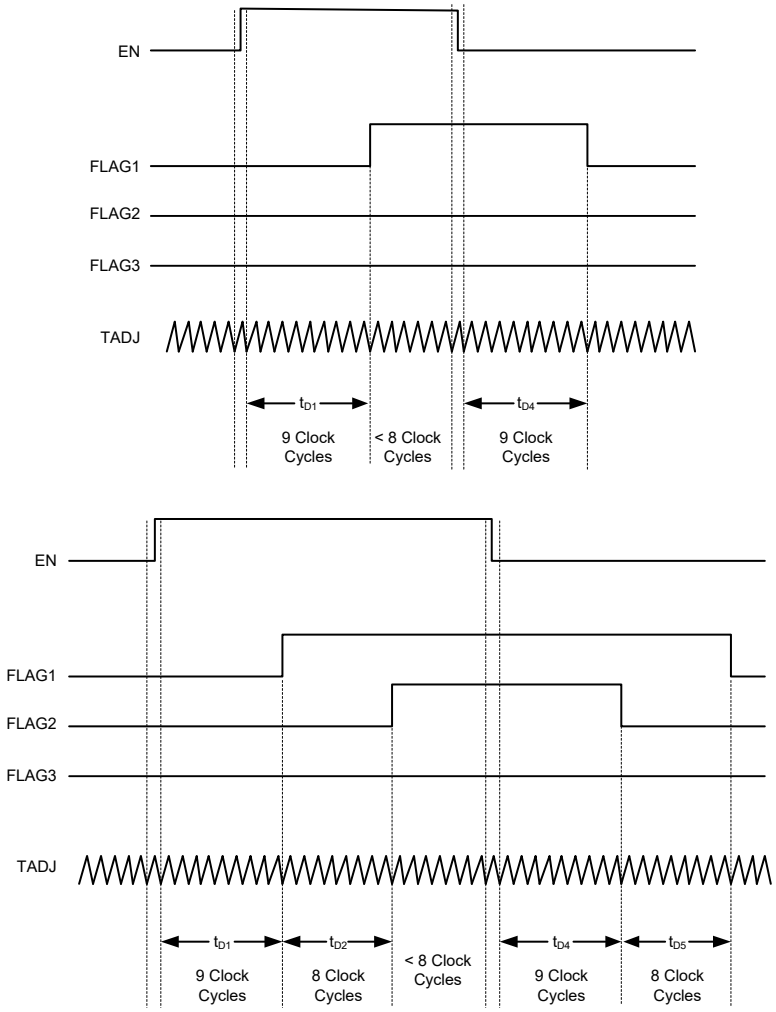


Figure 13. Incomplete Sequence Timing, INV Low

The Sequencing with EN Pin Control

The timing sequence of the SGM822 is controlled by the enable (EN) pin. After power-on, all the flags are held low until the precision EN pin is pulled high. After EN is pulled high, the power-up sequence begins to execute.

When EN is pulled low, the power-down sequence will execute. After the third flag (FLAG3) corresponding delay time expires, FLAG3 is pulled low. The second and first flags will then be pulled low after their appropriate delays.

INV Pin Setting the Logic Output

When the INV pin is tied to a logic low, the flag output is active high. When the INV pin is tied to a logic high, the flag output is active low.

APPLICATION INFORMATION

Pulling up Flag Pins to Independent Power Supply

The SGM822 contains three open-drain output flags which need external pulled-up resistors, for example 100kΩ pull-up resistors. This part is designed to protect the flag output pins from damaging if these pins are shorted to VCC for a short period.

For some application scenarios, the flag output voltage needs to be different from the VCC voltage. The separate flag power supply is used to pull up the open-drain outputs. With this method, each flag is pulled high to the required level of the controlled power supplies. The user must make sure the flag supply voltage is within the recommended operating range.

Design Example

In this example, the SGM822 is used to implement a power-up (1 - 2 - 3) and power-down (3 - 2 - 1) sequence of three power supplies.

Design Requirements

For this design example, use the parameters listed in Table 1.

Design Procedure

A timing capacitor of C_{ADJ} = 10nF generates typical delay time t_{D2} and t_{D3} of 10.4ms and t_{D1} of between 11.7ms and 13ms. Connect the INV pin to GND so that the output flags are active high. See Adjustable Timing for calculating the value for C_{ADJ}.

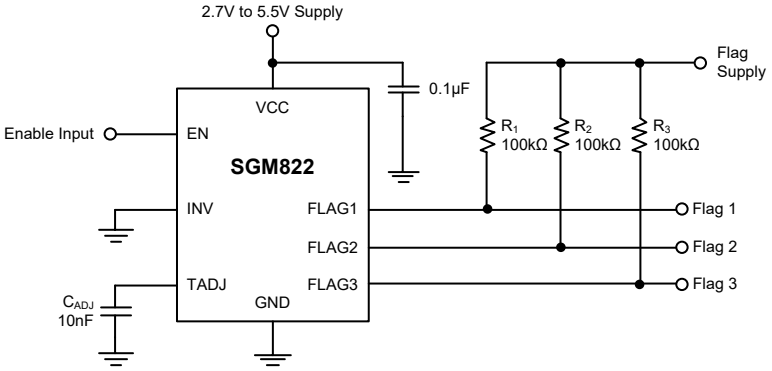


Figure 14. Sequencing Using Independent Flag Supply

Table 1. Design Parameters

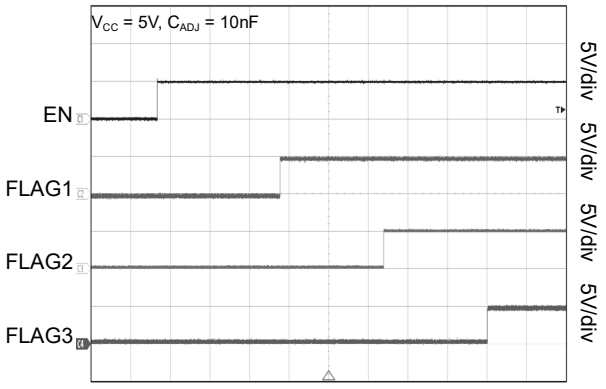
Design Parameter	Example Value
Input Supply Voltage Range	2.7V to 5.5V
Flag Output Voltage, EN high	Input Supply
Flag Output Voltage, EN low	0V
Flag Timing Delay, t_{D1}	11.7ms - 13ms
Flag Timing Delay, t_{D2} and t_{D3}	10.4ms
Power-Up Sequence	1 - 2 - 3
Power-Down Sequence	3 - 2 - 1

Table 2. Evaluation Board Bill of Materials

Ref Des	Description	Case Size	Manufacturer	Manufacturer P/N
U_1	SGM822 Sequencer	MSOP-8/UTDFN-1.5×1.5-8L	SGMICRO	XXX
R_1	100kΩ	0603	Vishay Dale	CRCW06031003F-e3
R_2	100kΩ	0603	Vishay Dale	CRCW06031003F-e3
R_3	100kΩ	0603	Vishay Dale	CRCW06031003F-e3
C_{ADJ}	10nF ±5% 50V C0G	0603	Murata	GRM1885C1H103JA01D

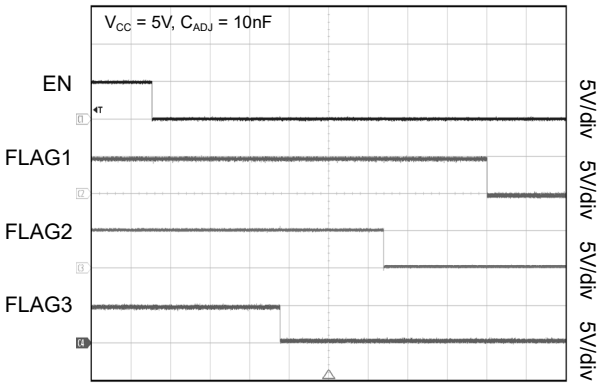
APPLICATION CURVES

Power-Up Sequence



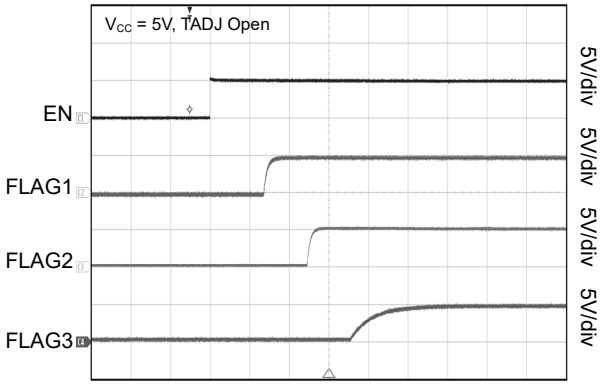
Time (4ms/div)

Power-Down Sequence



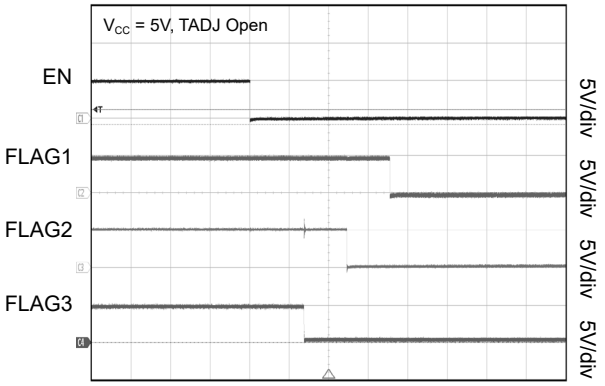
Time (4ms/div)

Power-Up Sequence



Time (20μs/div)

Power-Down Sequence



Time (20μs/div)

LAYOUT GUIDELINES

An input capacitor is not necessary but recommended to avoid the possible noise effect which might be present on the VCC pin. A 0.1μF ceramic capacitor may be placed as close as possible to the VCC pin.

Connect pull-up resistors between the flag output pins and a positive input supply (VCC or an independent flag supply). Minimal trace length is recommended to avoid the unexpected noise from the environment. A typical value for the pull-up resistors is 100kΩ.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

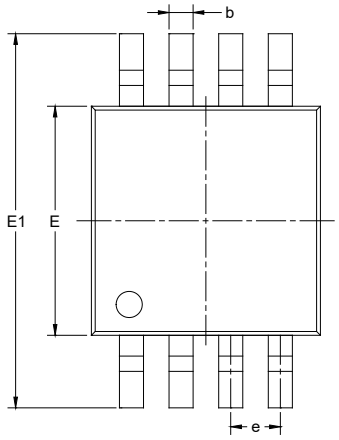
APRIL 2024 – REV.A.1 to REV.A.2	Page
Added UTDFN-1.5×1.5-8L package	All
Changed Electrical Characteristics section	4

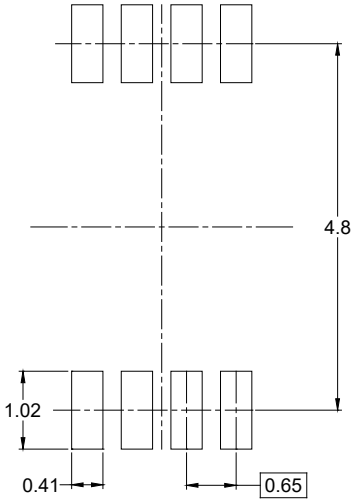
AUGUST 2020 – REV.A to REV.A.1	Page
Changed Absolute Maximum Ratings section	2
Changed Electrical Characteristics section	4
Changed Enable Circuit section	10

Changes from Original (JULY 2020) to REV.A	Page
Changed from product preview to production data	All

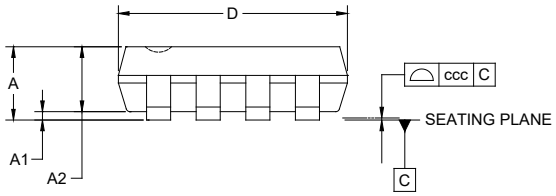
PACKAGE OUTLINE DIMENSIONS

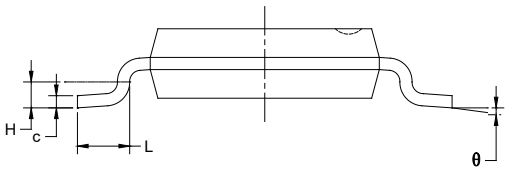
MSOP-8





RECOMMENDED LAND PATTERN (Unit: mm)



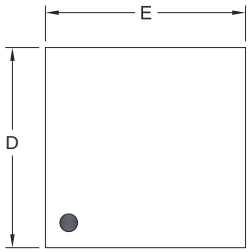


Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	-	-	1.100
A1	0.000	-	0.150
A2	0.750	-	0.950
b	0.220	-	0.380
c	0.080	-	0.230
D	2.800	-	3.200
E	2.800	-	3.200
E1	4.650	-	5.150
e	0.650 BSC		
L	0.400	-	0.800
H	0.250 TYP		
θ	0°	-	8°
ccc	0.100		

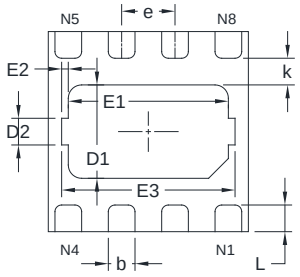
NOTES:
1. This drawing is subject to change without notice.
2. The dimensions do not include mold flashes, protrusions or gate burrs.
3. Reference JEDEC MO-187.

PACKAGE OUTLINE DIMENSIONS

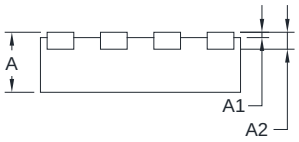
UTDFN-1.5×1.5-8L



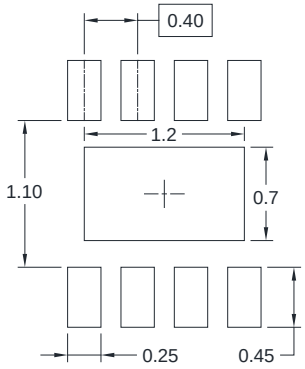
TOP VIEW



BOTTOM VIEW



SIDE VIEW



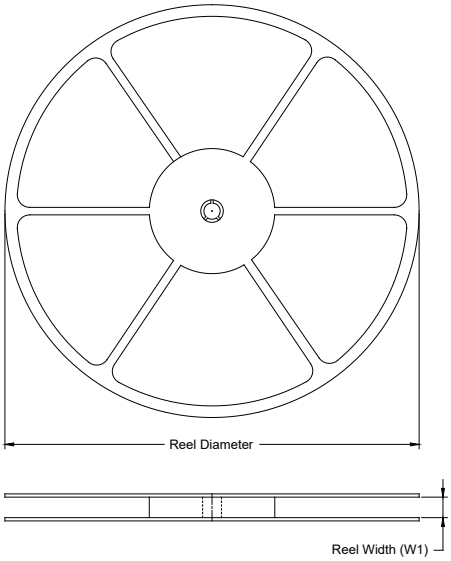
RECOMMENDED LAND PATTERN

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.400	0.500	0.016	0.020
A1	0.000	0.050	0.000	0.002
A2	0.127 REF		0.005 REF	
D	1.450	1.550	0.057	0.061
D1	0.600	0.800	0.024	0.031
D2	0.200 REF		0.008 REF	
E	1.450	1.550	0.057	0.061
E1	1.100	1.300	0.043	0.051
E2	0.050 REF		0.002 REF	
E3	1.200	1.400	0.047	0.055
k	0.200 REF		0.008 REF	
b	0.150	0.250	0.006	0.010
e	0.400 BSC		0.016 BSC	
L	0.150	0.250	0.006	0.010

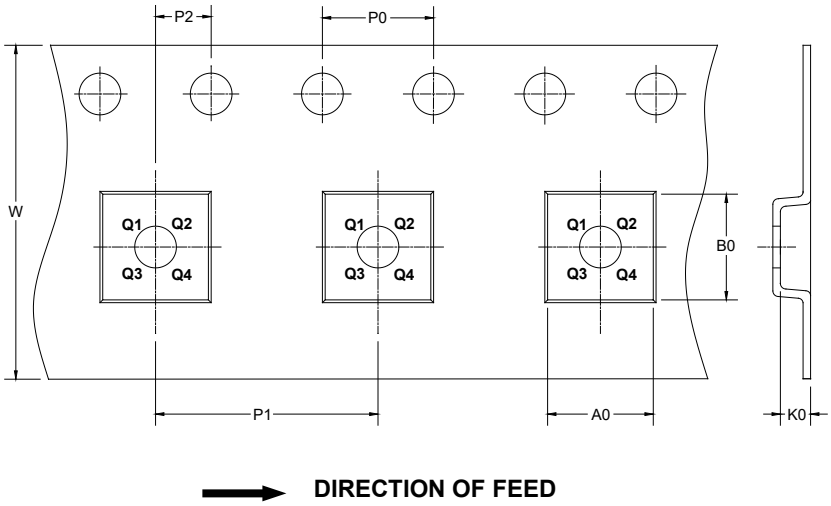
NOTE: This drawing is subject to change without notice.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



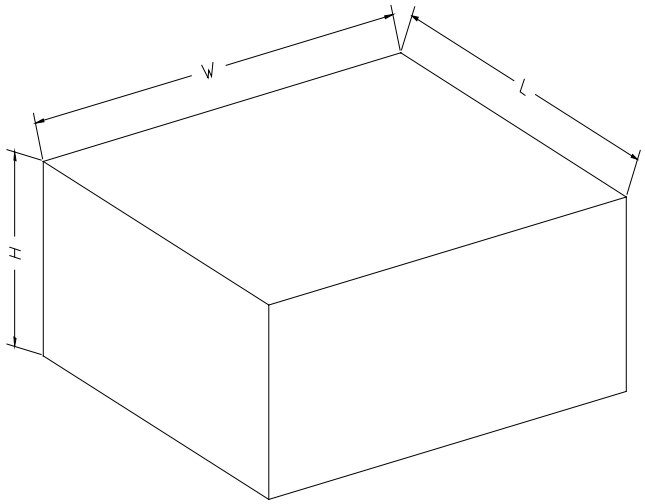
NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
MSOP-8	13″	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1
UTDFN-1.5×1.5-8L	7"	9.0	1.70	1.70	0.75	4.0	4.0	2.0	8.0	Q1

DD0001

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7″ (Option)	368	227	224	8
7″	442	410	224	18
13″	386	280	370	5

DD0002